

TI Designs

Power Line Communication Motherboard with AC Mains Line Coupling



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Design Resources

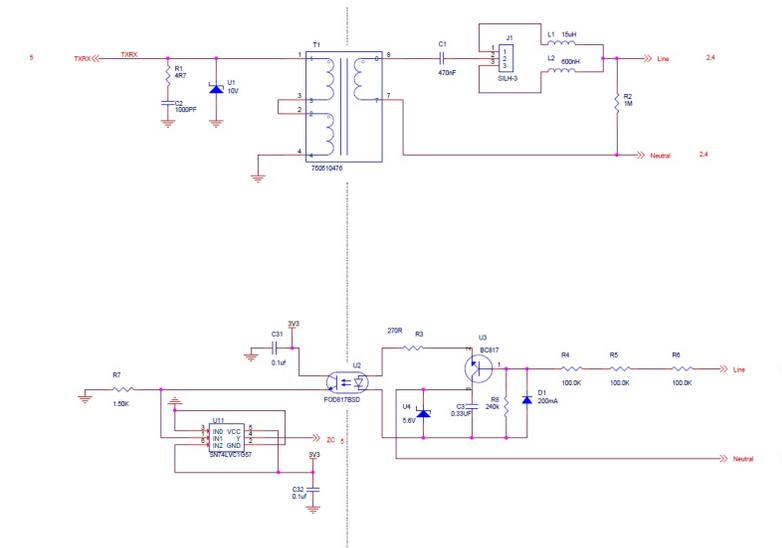
TIDA-00192 Tools Folder	Tool Folder Containing Design Files
TIDM-SOMPLC-F28PLC83	Related TI Design
TIDM-SOMPLC-F28M35-F28M35	Related TI Design
PTH08080W	Product Folder
SN74HC03	Product Folder
SN74LVC1G57	Product Folder
TPD2E001	Product Folder

Design Features

- Line Coupling Circuitry to Connect to Mains Power
- 15-V Input Voltage
- Supports CENELEC, FCC, and ARIB Frequency Bands
- Supports PRIME, G3, and IEEE-1901.2 PLC industry Standards
- USB Serial Port
- 5-V and 3.3-V Power Conversion
- Zero Crossing Circuitry
- 34-pin Mini-Header Provides Flexibility for Interfacing to Custom Board and Other TI Designs such as SOMPLC-F28PLC83 and SOMPLC-F28M35



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1 System Description

The Power Line Communication (PLC) motherboard is designed to complement TI Designs [TIDM-SOMPLC-F28PLC83](#) and [TIDM-SOMPLC-F28M35-F28M35](#). The PLC motherboard implements the key AC line coupling circuitry necessary for the System on Module (SoM) to connect to the mains power (line power). The PLC motherboard also includes expansion headers for RF modules, which simplifies the development of a combined PLC+RF system.

The hardware for TIDA-00192 can be ordered at [TIDA-00192](#).

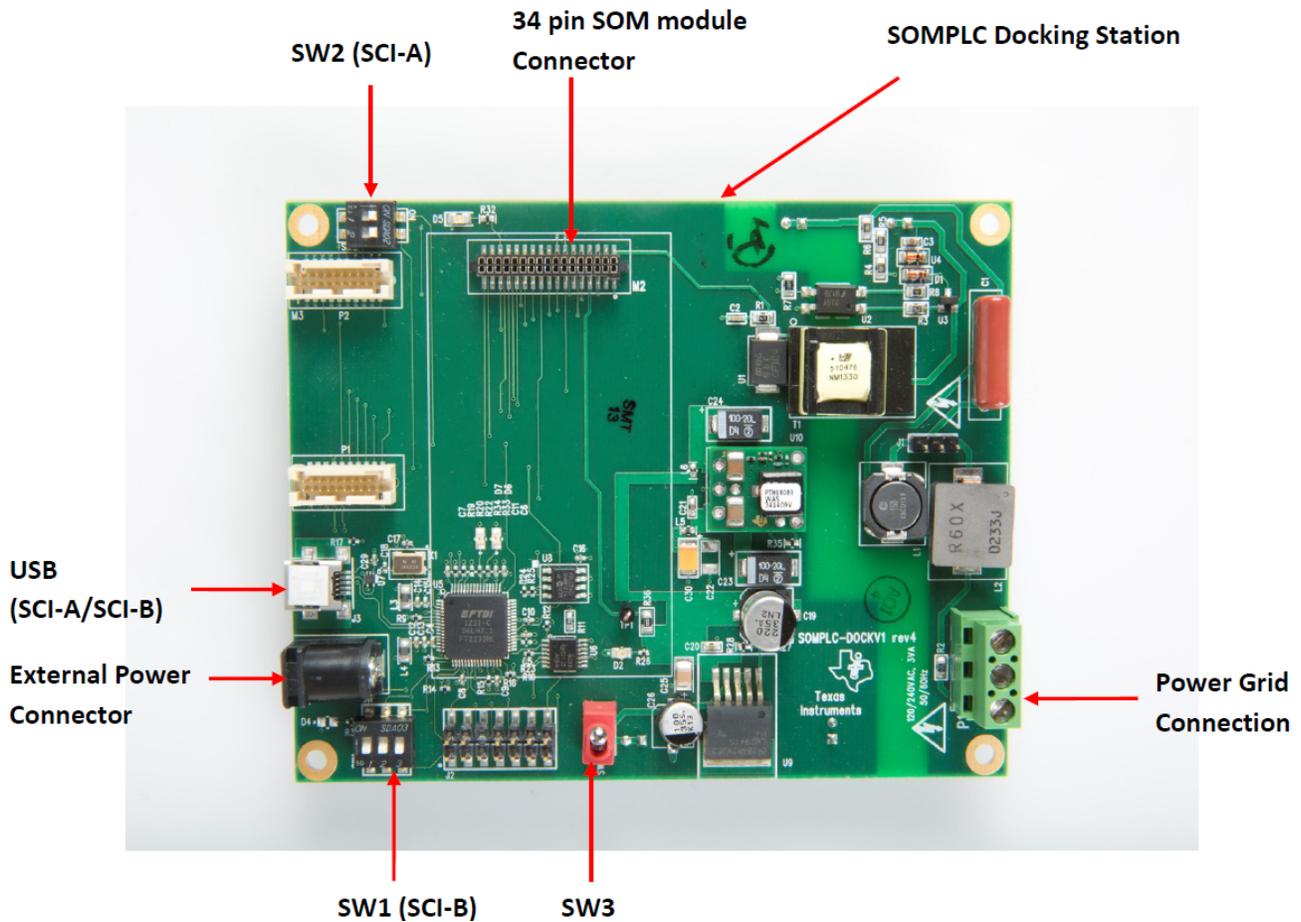


Figure 1. TIDA-00192 PLC Docking Board

The PLC docking board contains the following main components and supported features:

- The 34-pin connector provides flexibility to plug in SOM modules to evaluate CENELEC/FCC/ARIB solutions. Some of the supported SOM modules are [TIDM-SOMPLC-F28PLC83](#) and [TIDM-SOMPLC-F28M35-F28M35](#).
- Examples of operating frequency range are shown below:

Band	CENELEC				FCC			ARIB	
	A	B	BC	BCD	Low	High	Full	Low	High
Frequency (kHz)	35.9 to 90.6	98.4 to 121.9	98.4 to 137.5	98.4 to 146.9	145.3 to 314	314 to 478.1	145.3 to 478.1	10 to 200	20 to 450

- Data rates from 5.592 kbps to 34.16 kbps (at 36 tones per symbol) for Cenelec A band and up to 289 kbps for FCC band
- Transmission with OFDM and FEC
- Number of used data carriers up to 36 for Cenelec and 72 for FCC
- Differential phase modulation (ROBO/DBPSK/DQPSK/D8PSK)
- Reed Solomon encode/decode and repetition code
- Convolutional encoder/Viterbi decoder
- Bit interleaving for noise effect reduction
- CRC5 in FCH and CRC16 in data for error detection
- Data randomization for uniform power distribution
- Tone mask for SFSK coexistence
- Adaptive tone mapping and transmit power control
- Automatic gain control
- Zero-crossing detection
- Supports G3 PHY, MAC and adaptation layer
- SCI-A/SCI-B serial interface to communicate to PC GUI

2 34-Pin Definition

The interfaces supported on this module are the following:

REQUIRED CONNECTIONS	OPTIONAL CONNECTIONS
<ul style="list-style-type: none"> • SCI (UART) • Line • 15V • 3V3 • GND 	<ul style="list-style-type: none"> • ADC • GPIOs • SCI (UART) • CAN • SPI • I2C • Zero Cross • Analog GND

Table 1. 34-Pin Connector

PIN#	NAME	I/O	ELECTRICAL	DESCRIPTION
1	L1	I/O	0V (GND)	Neutral (Analog Ground), connected to the PL coupler
2	L2	I/O	0V (± 6 -V Peak)	Analog PLC signal, connected to the PL coupler
3	NC	NC	–	Unused
4	NC	NC	–	Unused
5	GND	–	–	Ground
6	GND	–	–	Ground
7	V15	–	15 V to 18 V	Power supply pin (15 V). Peak current 400 mA in transmit mode (average 100 mA).
8	3V3	–	3.14 V to 3.47 V	CPU and Logic Digital Power pin (3.3V). Max current 1000 mA.
9	EN	I-I/O	-0.3 V to ($V_{CC} + 0.3$ V)	System Enable (logical level, active High). Controls Power up/down function of the module. When Low, the module goes to power down mode. This feature is NOT yet implemented in software or GPIO13.
10	ZC	I	-0.5 V to 6.5 V	Buffered ZC input. This input MUST be isolated from the power line before entering this pin.
11	RX-A	I	-0.3 V to ($V_{CC} + 0.3$ V)	Asynchronous serial host-transmit, SCI-A
12	TX-A	O	-0.3 V to ($V_{CC} + 0.3$ V)	Asynchronous serial host-receive, SCI-A
13	Phase B/GPIO	I-I/O	-0.3 V to ($V_{CC} + 0.3$ V)	Phase B Enable signal (for 3 phase selection) or GPIO5
14	Phase C/GPIO	I/O	-0.3 V to ($V_{CC} + 0.3$ V)	Phase C Enable signal (for 3phase selection) or GPIO10
15	SDAA	I/O	-0.3 V to ($V_{CC} + 0.3$ V)	I ² C data pin
16	SCLA	I	-0.3 V to ($V_{CC} + 0.3$ V)	I ² C clock pin
17	ADC-B0	I	-0.3 V to ($V_{CC} + 0.3$ V)	Unused ADC input. (ADC-B0).
18	AGND	–	–	Analog ground
19	GPIO26	I/O	-0.3 V to ($V_{CC} + 0.3$ V)	Unused multi-purpose IO, GPIO26
20	GND	–	–	Ground
21	GPIO27	I/O	-0.3 V to ($V_{CC} + 0.3$ V)	Unused multi-purpose IO, GPIO27
22	GND	–	–	Ground
23	CAN RX/GPIO	I-I/O	-0.3 V to ($V_{CC} + 0.3$ V)	CAN RX interface or GPIO30
24	CAN TX/GPIO	O-I/O	-0.3 V to ($V_{CC} + 0.3$ V)	CAN TX interface or GPIO31
25	CLKA/GPIO	I	-0.3 V to ($V_{CC} + 0.3$ V)	SPI clock or general purpose I/O (GPIO18).
26	STEA/GPIO	I	-0.3 V to ($V_{CC} + 0.3$ V)	SPI Slave Transmit Enable or general purpose I/O (GPIO19).
27	SIMOA/GPIO	I	-0.3 V to ($V_{CC} + 0.3$ V)	SPI Slave in, Master out or general purpose I/O (GPIO16).
28	SOMIA/GPIO	O	-0.3 V to ($V_{CC} + 0.3$ V)	SPI Master in, Slave out or general purpose I/O (GPIO17).
29	System RESET	I	-0.3 V to ($V_{CC} + 0.3$ V)	Reset of SOMPLC (active Low)
30	GPIO04	I/O	-0.3 V to ($V_{CC} + 0.3$ V)	Unused multi-purpose IO pin, GPIO04.
31	NC	NC	–	Unused
32	NC	NC	–	Unused
33	RX-B	I	-0.3 V to ($V_{CC} + 0.3$ V)	Asynchronous serial host-receive, SCI-B
34	TX-B	O	-0.3 V to ($V_{CC} + 0.3$ V)	Asynchronous serial host-transmit, SCI-B

3 34-Pin Connector Mechanical Specification

The connectors used in this design are as follows:

- A female 0.05 mm receptacle (2 rows \times 17 pins) should be used on the host board to mate with the SOMPLC module.
 - This connector is keyed and should follow the appropriate orientation as the male connector.
 - An example part that fits this design is a Sullins Connector Solutions [Part Number: SFH31-NPPB-D17-SP-BK](#), [Digikey Part Number:S9117-ND](#).

The top view of the female connector placed on the host board is shown in [Table 2](#).

Table 2. 34-Pin Female Connector Top View

	1	2
	3	4
	5	6
	7	8
	9	10
	11	12
	13	14
	15	16
	17	18
	19	20
	21	22
	23	24
	25	26
	27	28
	29	30
	31	32
	33	34

4 Test Procedure

In order to test the SOM modules, the operator will need the following items (the test procedure will be the same, depending on the SOM module under test, but the results will vary):

- A host computer running Windows XP or Windows 7 and two available USB ports
- 2 TMDSPCLC docking boards
- 2 PLC SOM modules (SOMPLC-F28PLC83, SOMPLC-F28M35.....)
 - To test the CENELEC band, 2 SOMPLC-F28PLC83 modules are required
 - To test the FCC band, 2 SOMPLC-F28M35 modules are required
- 15-V external power supply for each docking station
- Power line connector for each docking station
- USB cable for connecting to the host PC for each docking station
 - A single host PC can be shared between the two kits
- Zero Configuration GUI
 - Requires a modified .config file

4.1 Hardware Setup

This reference design can be configured for multiple applications. The steps on how to setup the design hardware are as follows:

1. Ensure the system is unpowered.
2. Connect the AC power cable to Line and Neutral of connector P1 as shown in [Figure 2](#) and [Figure 3](#) (ensure Line and Neutral connections are not shorted).

NOTE: Depending on the manufacturer, the power cord can have markings on the cord for Line (See [Figure 3](#)).

	<p>Danger High Voltage</p>	<p>Electric shock possible when connecting board to live wire.</p>
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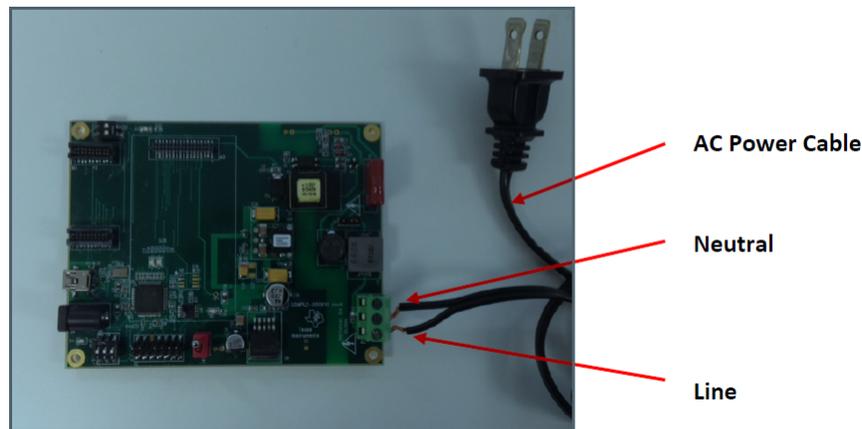


Figure 2. AC Power Cable Connections

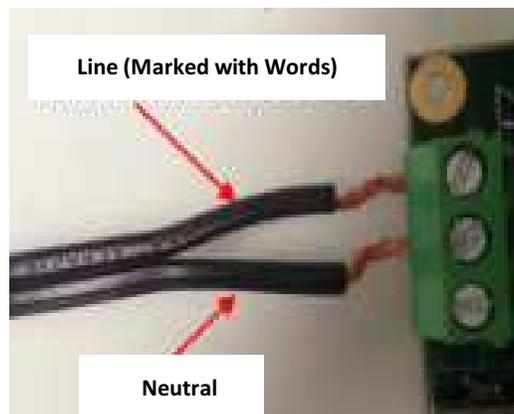


Figure 3. Neutral and Line Connections

3. Plug in the corresponding SOM module (CENELEC/FCC/ARIB) into the 34-pin connector as shown in [Figure 4](#). In [Figure 4](#), SOMPLC-F28PLC83 is plugged onto the dock.

NOTE: Refer to the respective SOM Module Guide for steps to program each SOM module.



Figure 4. Dock + SOMPLC-F28PLC83 Module Plugged

4. Depending on the type of SOM module plugged into the dock, the jumper settings for J1 required for standard operation are shown in [Table 3](#).

Table 3. J1 Jumper Settings

BAND	J1 JUMPER SETTING
CENELEC Band	2,3
FCC Band	1,2

5. Details of SCI-A/SCI-B jumper settings for UART communication with a PC can be found in the following paragraphs.

UART SCI Communication

In order to use the SCI USB interface, the host must be configured with the following parameters:

Baud Rate = 57600

Message Data Bits = 8

Stop Bits = One

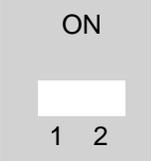
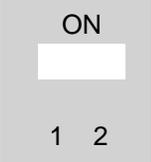
Parity = None

Handshake = None

RTS Enable = True

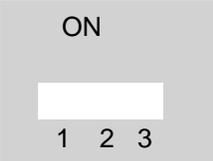
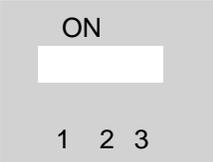
SCI A Communication (SW2 Positions)

SCI A communication to Intermediate GUI can be selected using the Switch SW2. The available settings are described as follows:

	<p>SCI A-EXT Position 1: OFF Position 2: OFF</p>
	<p>SCI A – USB (Default Setting) Position 1: ON Position 2: ON</p>

SCI B Communication (SW1 Positions)

SCI B communication to Intermediate GUI can be selected using the Switch SW2. The available settings are described as follows:

	<p>SCI B – EXT Position 1: OFF Position 2: OFF Position 3: OFF</p>
	<p>SCI B – USB Position 1: ON Position 2: ON Position 3: ON</p>

4.2 Power Up

- Connect 15-V wall mounted power supply to the AC receptacle of each kit.
- Turn ON Switch SW3 of each kit to power the boards.

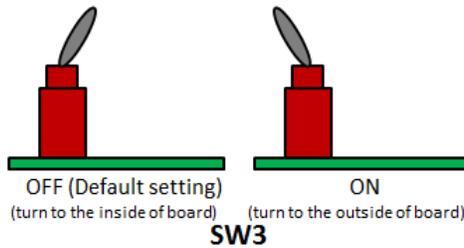


Figure 5. Switch SW3

4.3 Connecting to a PC

- Plug in the micro-USB to the kit and connect the USB cable to the PC (repeat this step for the second kit).

NOTE: There may be a dialog asking to install USB-Serial drivers. If there is a dialog asking to install USB-Serial drivers, install the drivers. The drivers can be found in the corresponding SW package downloaded from the SW section of the product web page. For example, if the G3 SW development package is downloaded from the product web page, then the drivers can be obtained from C:\Texas Instruments\G3DevelopmentEvalPackage\xxxx\XDS100 Drivers.

It is necessary to reboot the PC after the drivers are installed, even if there is no dialog in Windows to do so.

- Verify the modems have been installed correctly by using Microsoft Windows Device Manager (Start -> Control Panel -> System -> Device Manager -> Ports)

NOTE: The four ports in Figure 6 are for two boards.

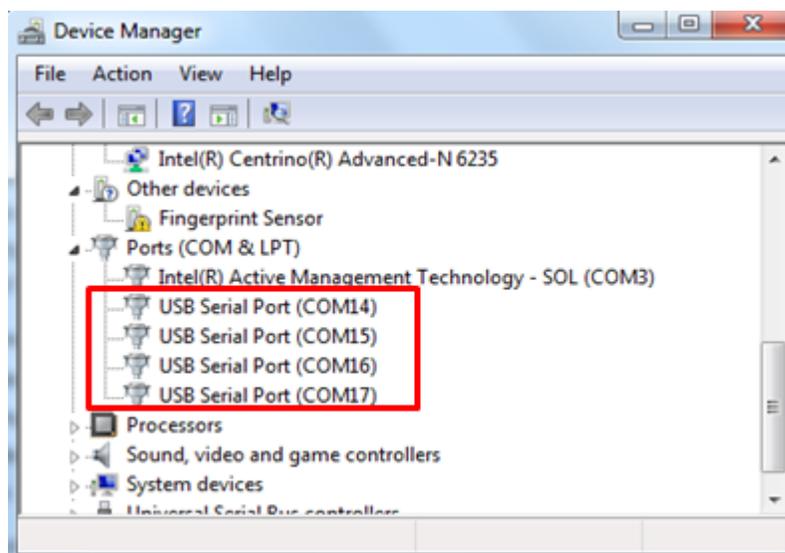


Figure 6. Serial Ports for Two Boards

4.4 Connection to Zero Configuration GUI

NOTE: Refer to the Zero Configuration User Guide in the PLC SW package for more details.

As shown in [Figure 7](#), Zero Configuration GUI (ZCG) is a Windows application that the designer can use to immediately start performing text and file transfers, examine the current system information, display the PHY parameters, change the PHY modulation, display the file and text transfer statistics, and display and save the log information.

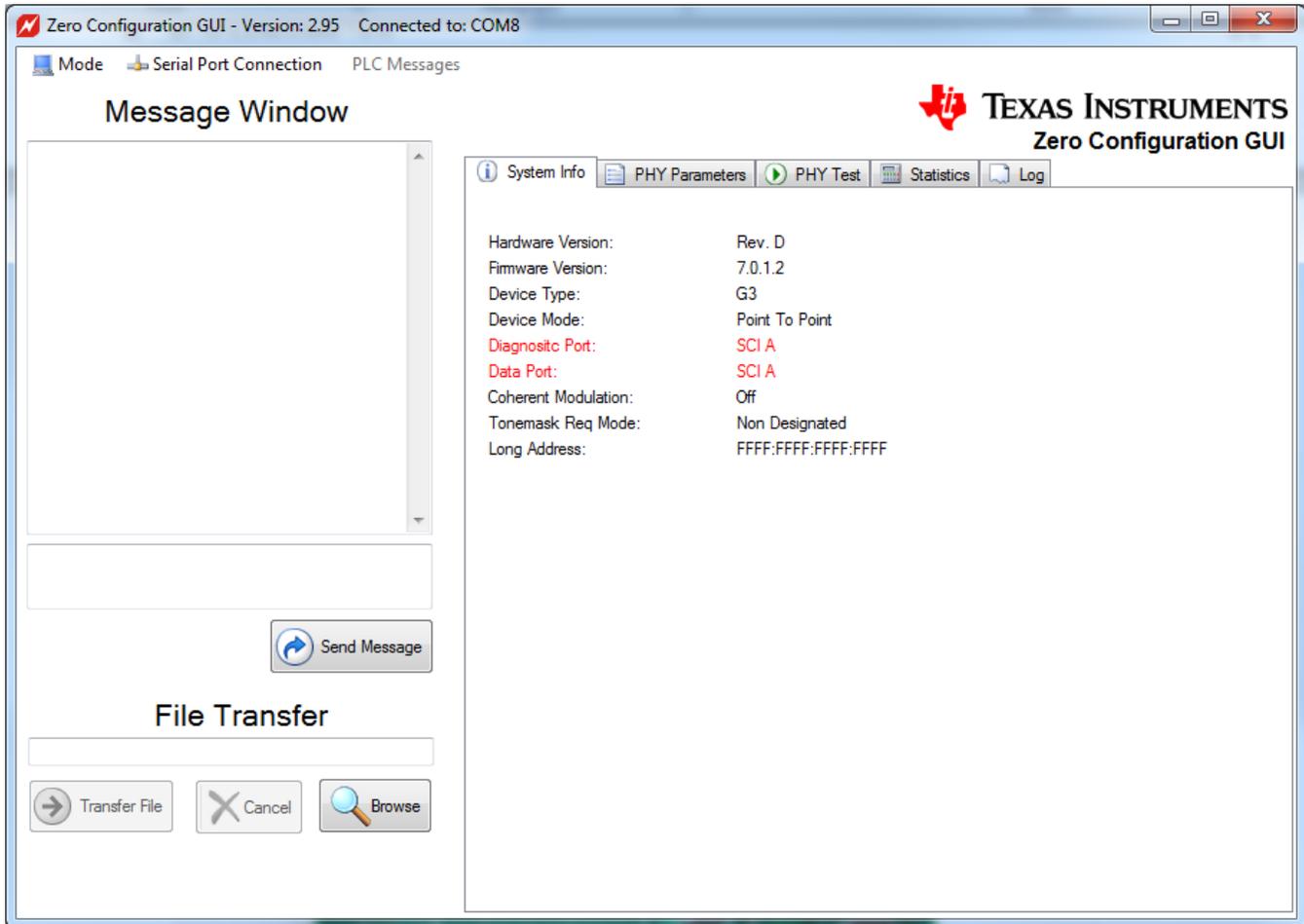


Figure 7. Zero Configuration GUI

4.4.1 Zero Config GUI Configuration

There is no software or PLC configuration needed to use the Zero Configuration GUI.

NOTE: There is an assumption is that the USB ports (SCI-A) on the PLC are being used.

The first available COMM port on the PC, which may be a USB to Serial Port or a standard COMM port, is used to connect to the PCL.

If no available serial ports are found on the PC, the ZCG displays an error, as shown in [Figure 8](#).

If the PLC is reset while connected to the ZCG, the ZCG must be restarted or reconnected using the Serial Port Connection menu.

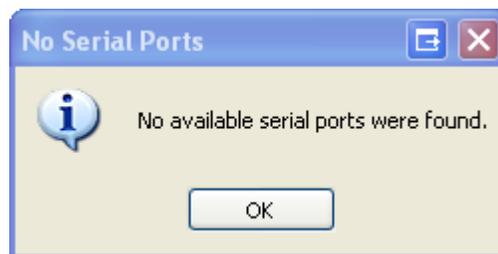


Figure 8. No Available Serial Ports Error

If there is no response on the COMM port selected, the Zero Configuration GUI will display a timeout error and remain active, as shown in [Figure 9](#).

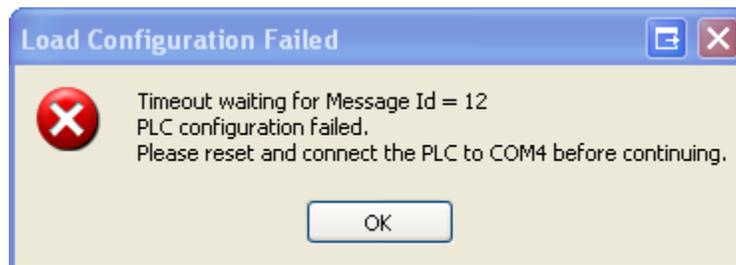


Figure 9. Timeout Error

If the PLC is connected to another COMM port, use the use the “Serial Port Connection” drop down menu to connect to the desired COMM port. If the PLC is not connected, connect the PLC to the desired port and try again. If the PLC is connected to the correct COMM port, reset the PLC.

4.4.2 Main Screen

The ZCG consists of the main screen where text and file transfers may be performed, as shown in [Figure 10](#). The tabs on the right display significant information about the PLC.

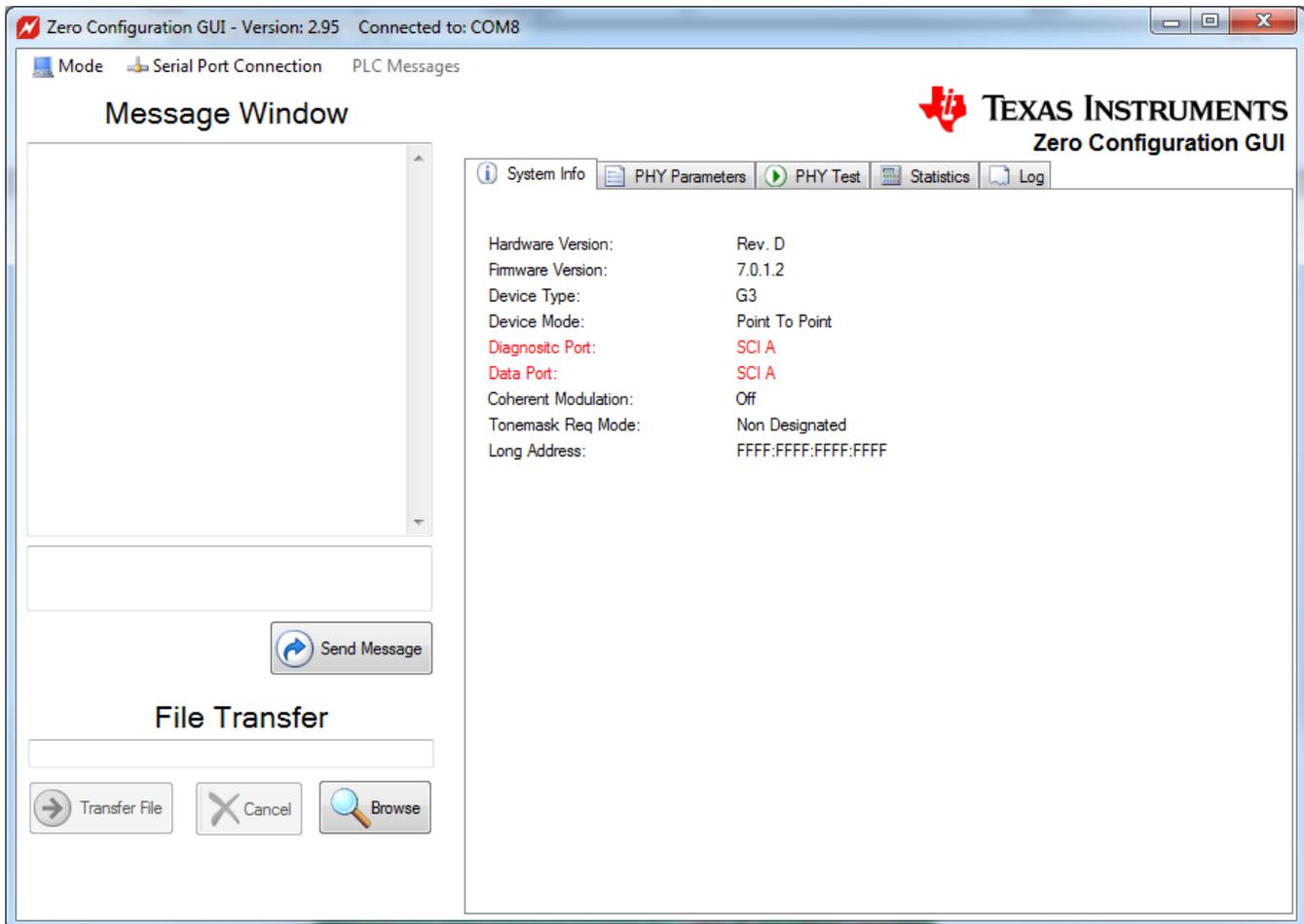


Figure 10. Zero Configuration GUI Main Screen

The COMM port attached to is displayed in the title bar. The first available and unopened COMM port is automatically chosen. The “Serial Port Connection” drop down menu may be used to change the selection to another COMM port.

The design engineer can use this screen to perform text message transfers and file transfers with another PLC controlled by the Zero Configuration GUI.

You may also change the mode by using the "Mode" drop down menu. There are two modes, Zero Configuration and Intermediate.

The Zero Configuration mode is the mode described in this reference design. Any available COMM port 1-## will work with the Zero Configuration GUI. The COMM port number does not have to be less than ten.

The Intermediate mode runs from a different dialog and gives the designer many more configuration options and functions to perform.

4.4.3 System Info Panel

The PLC system information is displayed in the first tab, as shown in [Figure 11](#).

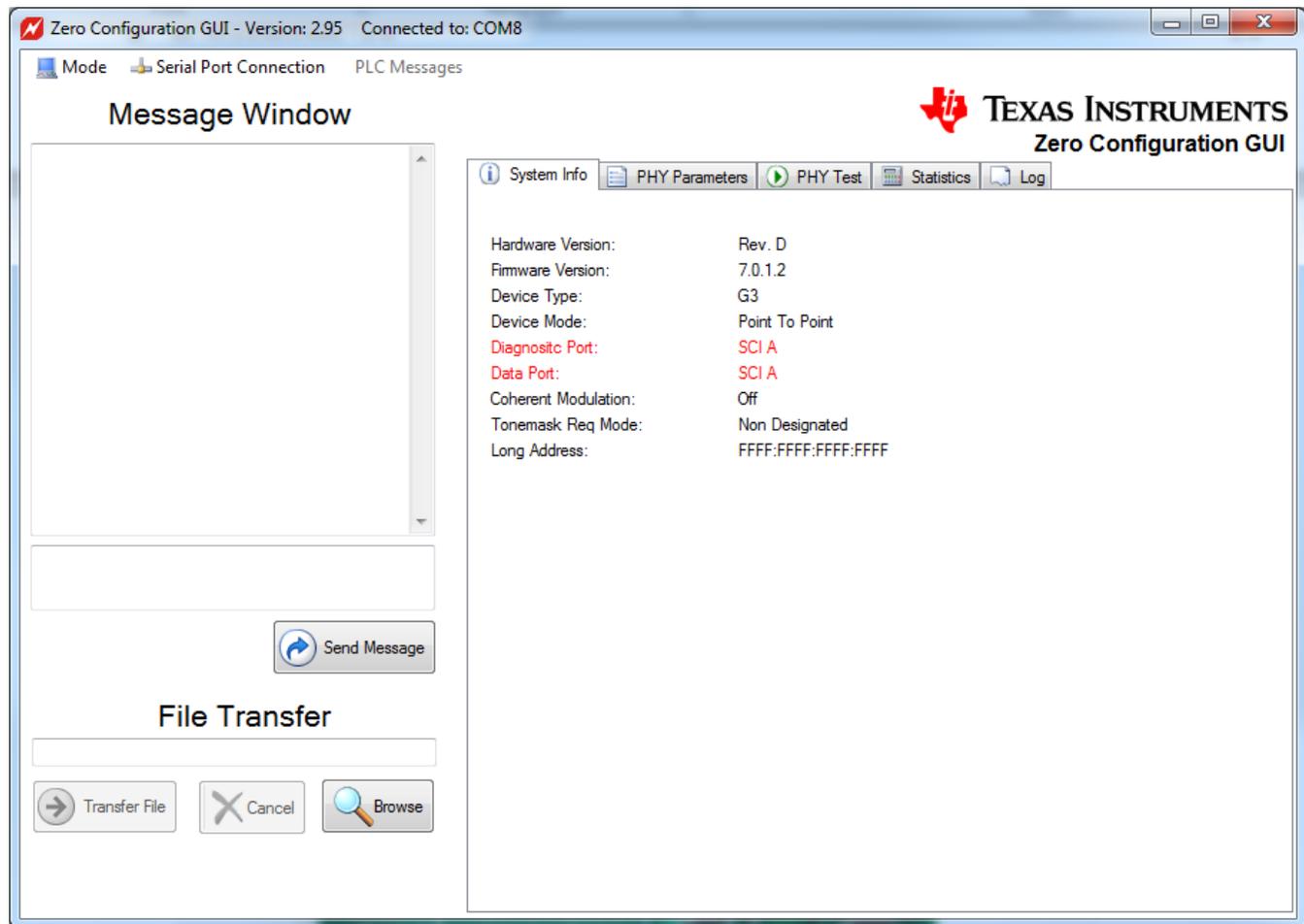


Figure 11. PLC System Information

Right clicking on the System Info panel will expose a context menu with one menu item: "Refresh System Information". The Refresh System Information menu item resends a system information request to the PLC and refreshes the System Info panel with the updated information.

Pressing "Ctrl S" will perform the same function, without displaying the context menu.

Any value changed will be displayed in red text.

4.5 Testing

NOTE: Testing was conducted with 2 SOMPLC-F28PLC83 SOM modules. Testing results will vary, depending on the PLC SOM module being tested.

- Ensure the boards are powered and connected to the PC. Launch the Zero Configuration GUI. When using one PC to operate the test, it is necessary to launch two instances, one for each modem.
- When the Zero Configuration GUI opens, ZCG uses the first available COM port to attach to a PLC.

NOTE: Ensure the Diagnostic Port and the Data Port are configured to SCI-A by selecting CTRL+A in the GUI window, as shown in [Figure 12](#).

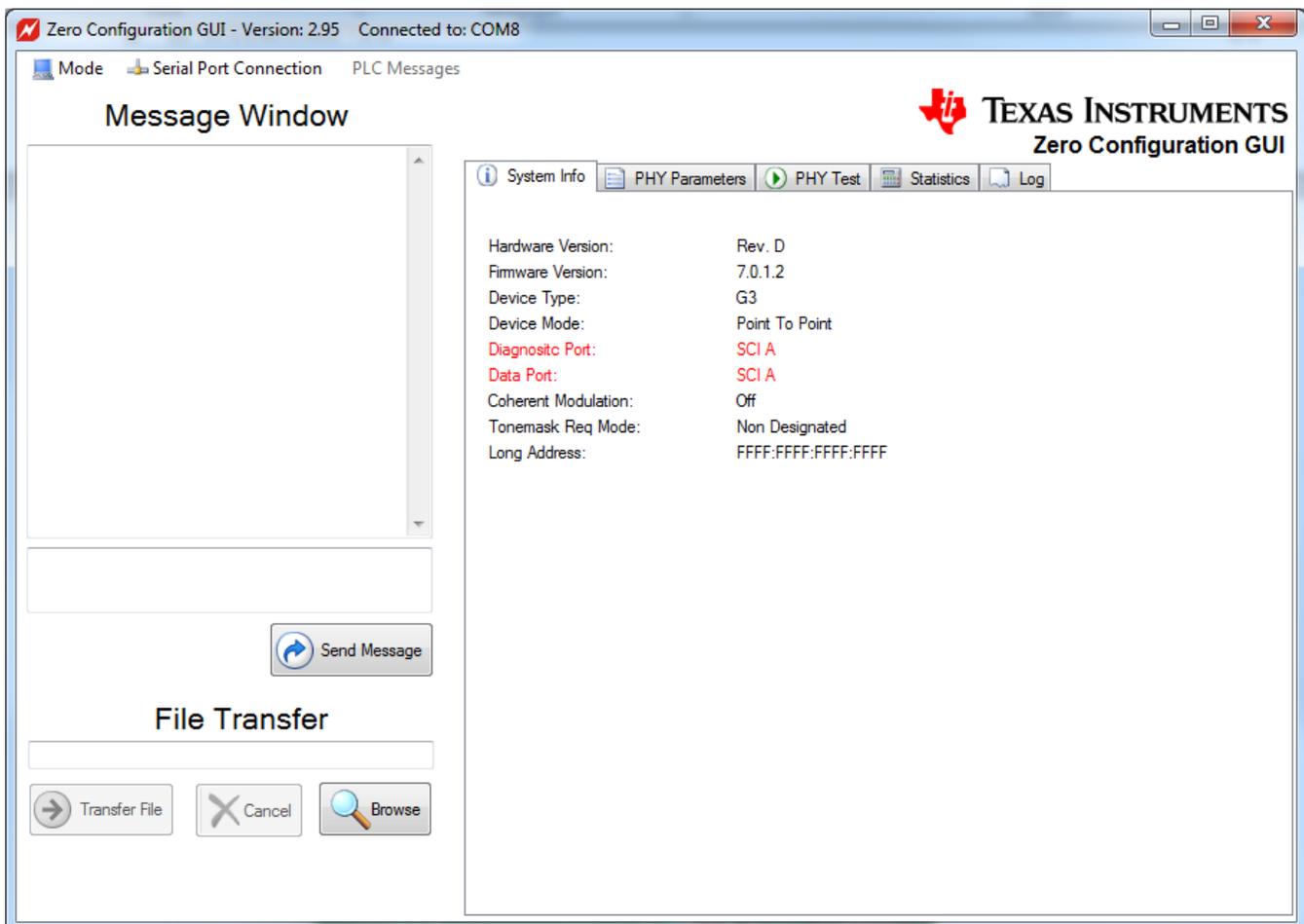


Figure 12. SCI-A Ports Configuration

- Connect each PLC kit to power line, as shown in [Figure 13](#). Please ensure that devices are connected on same power line phase.

	<p>Danger High Voltage</p>	<p>Use caution when connecting to the power grid. If there is concern about connecting to the power grid, a power strip can be used to connect the two modems together. In this case, the power strip does NOT need to be plugged into the power grid. Connect each PLC kit to power line . as shown in Figure 13.</p>
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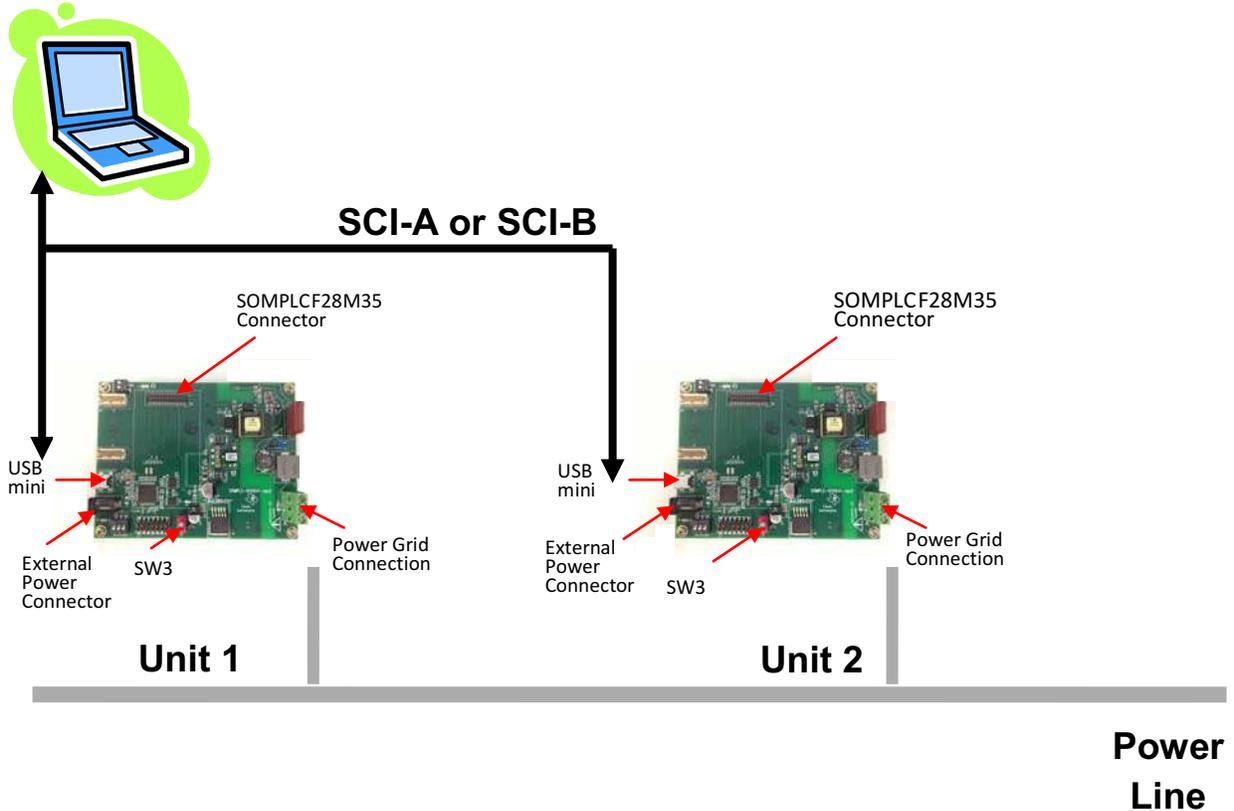


Figure 13. PLC Kits to Power Line Connections

- Enter the desired text into the Message Window.
- Press the Send Message button.
- The message will then be received by the other GUI, as shown in [Figure 14](#).

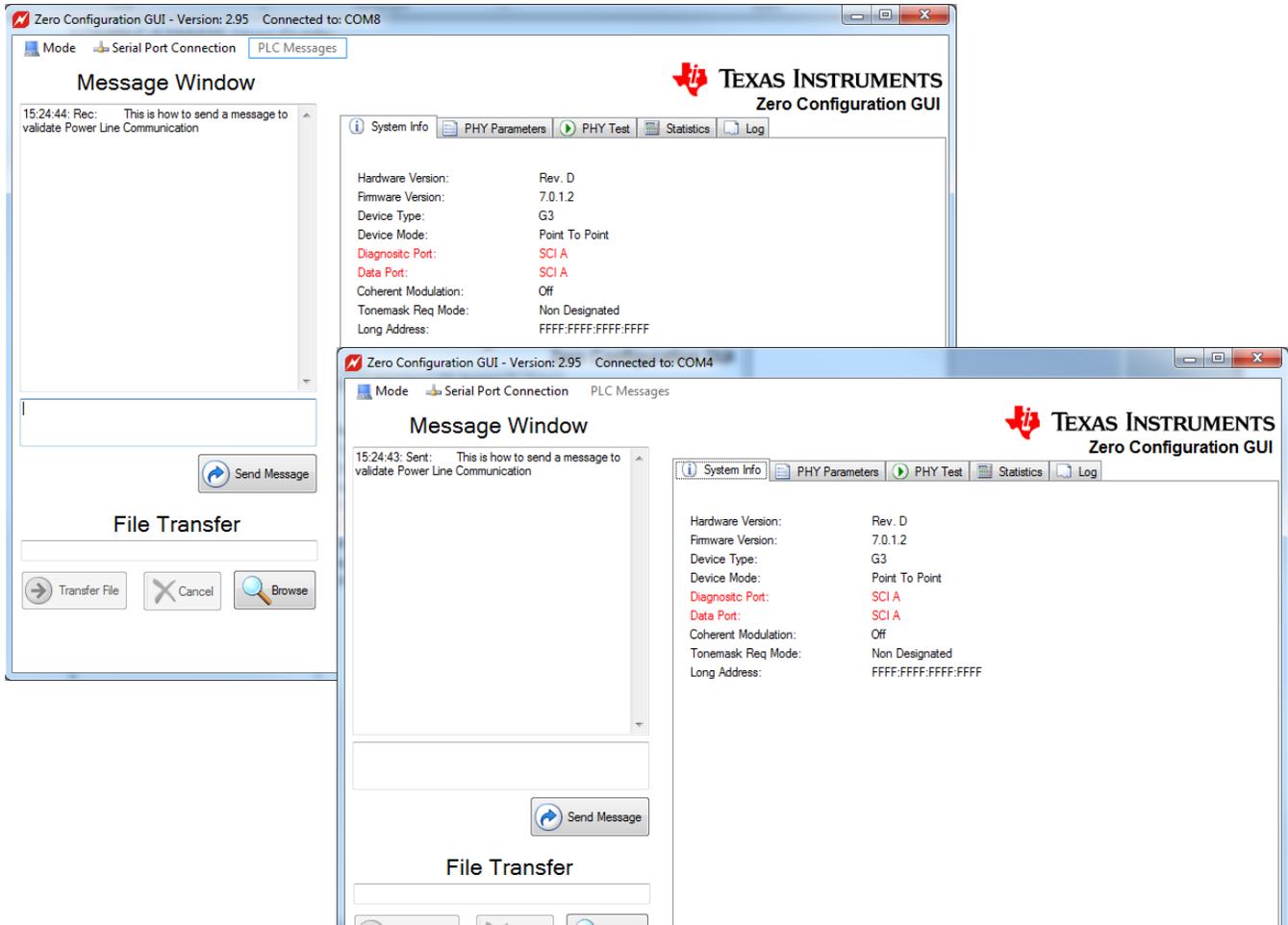


Figure 14. Send Message Dialog

- The File Transfer function contained in the bottom left hand corner of GUI can be utilized to transfers files, as shown in [Figure 15](#).

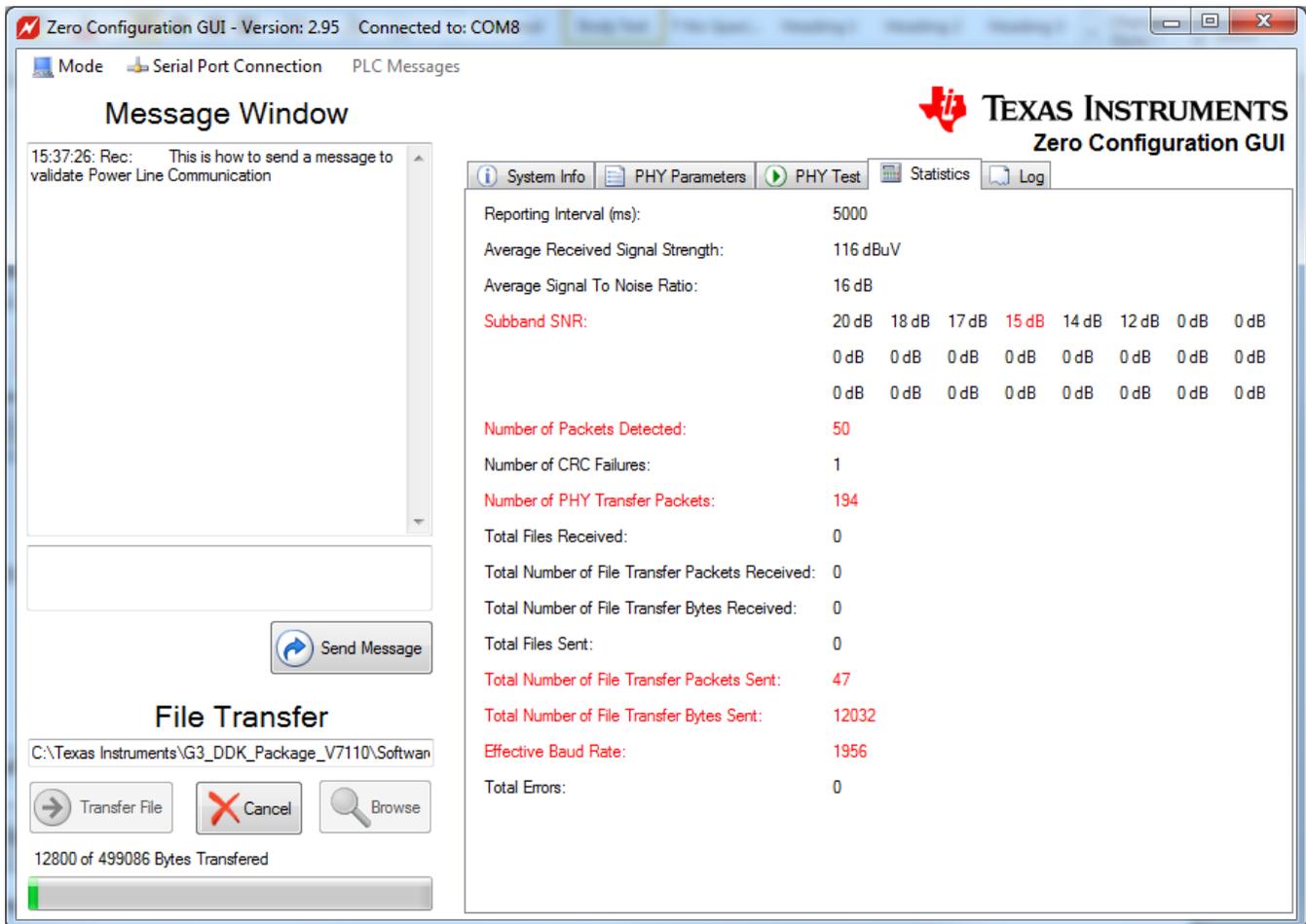


Figure 15. File Transfer Function Part 1

Click on the "Browse" button to display the standard Windows file chooser dialog to choose the file to transfer. Only one file at a time may be chosen for the file transfer.

After the file is chosen, click on the "Transfer File" button.

The other PLC must also be controlled by the Zero Configuration GUI.

When the transfer starts, the GUI will display a progress bar on both Zero Configuration GUIs. As shown in [Figure 16](#), the receiving Zero Configuration GUI displays the path and file name where the received file is being copied to. The user cannot change the directory path of the received file.

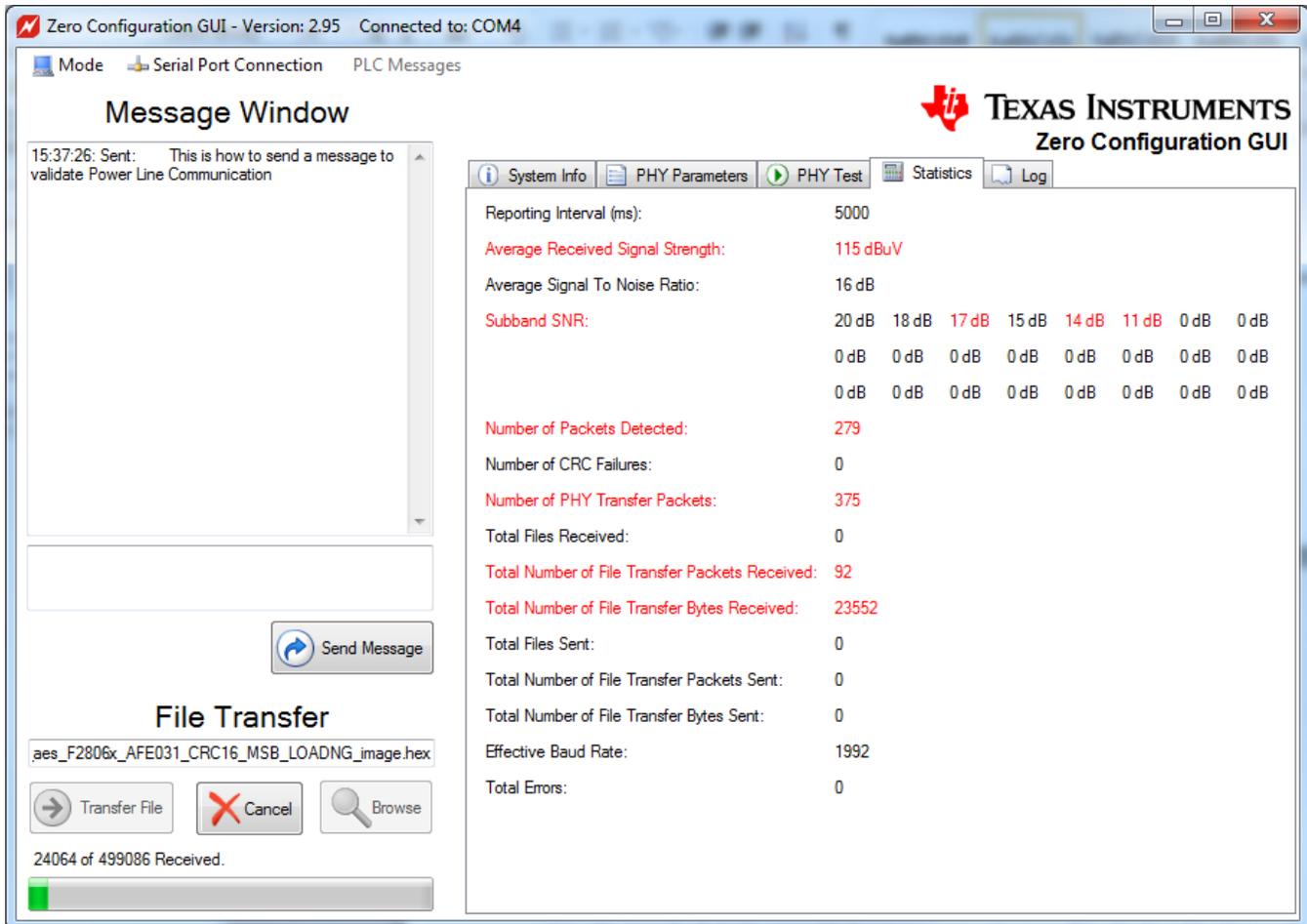


Figure 16. File Transfer Function Part 2

When the file transfer is complete, the message box below will be displayed on both Zero Configuration GUIs, as shown in [Figure 17](#).

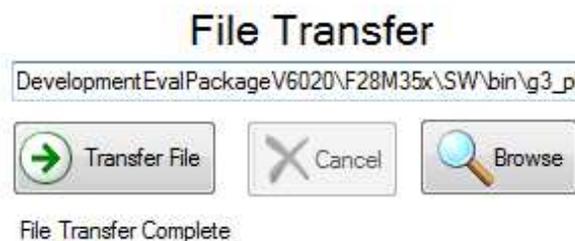


Figure 17. File Transfer Complete

If the file transfer fails, one of following message boxes is displayed by the sending GUI, as shown in [Figure 18](#) and [Figure 19](#).

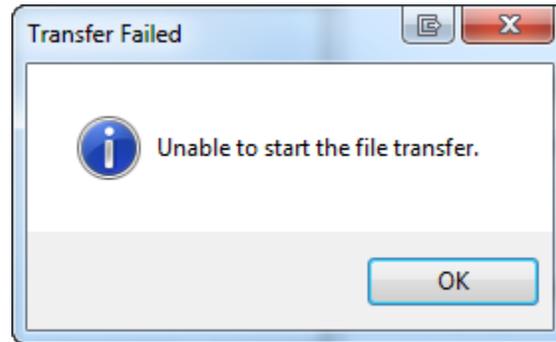


Figure 18. File Transfer Failure Message 1

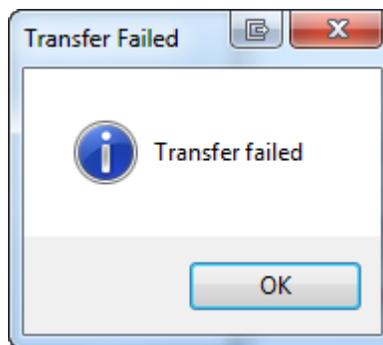


Figure 19. File Transfer Failure Message 2

The file transfer may be canceled by clicking on the "Cancel" button on either GUI.

5 Schematics

To download the schematics for the reference design, see the design files at [TIDA-00192](#).

6 Bill of Materials (BOM)
Table 4. BOM

Part No.	QTY.	Part Type	Part Reference	Vendor	Vendor PN	Description	Value	PCB Footprint	Tolerance	Voltage	Distributor Part No.
300-00047	1	CAP	C1	Panasonic	ECQ-E4474KF	0.47 μ F/400VDC METAL POLY CAP	470nF	Axial 0.591" (15.00mm) Spacing	0	400V	EF4474-ND
100-00025	1	CAP	C2	AVX	06035C102KAT*A	Capacitor,1000PF, 50 V,10%,X7R,0603	1000PF	C0603	0.1	50V	
100-00126	1	CAP	C3	Murata	GRM188R71C334KA01D	Capacitor,0.33 μ F,16V,10 %,0603, X7R	0.33 μ F	C0603	0.1	16V	490-3294-1-ND
300-00073	3	CAP	C4 C12 C14	Murata	GRM155R60J475ME87D	CAP CER 4.7 μ F 6.3V X5R 0402	4.7 μ F	C0402	0	6.3V	490-5408-2-ND
100-00108	11	CAP	C5 C6 C7 C8 C9 C10 C11 C13 C15 C16 C29	Kemet	C0402C104K4RACTU	Capacitor,0.1 μ F, X7R, 16 V, 0402, 10%	0.1 μ F	C0402	0.1	16V	399-3521-2-ND
300-00074	2	CAP	C17 C18	Kemet	C0402C270J5GACTU	CAP CERAMIC 27PF 50V NP0 0402	27PF	C0402	0	50V	399-1016-2-ND
300-00115	1	CAP	C19	Panasonic	EEE-1VA221UP	CAP ALUM 220 μ F 35V 20% SMD	220 μ F	Radial	0	35V	PCE3955CT-ND
300-00113	2	CAP	C20 C21	TDK	C1608Y5V1H104Z	CAP CER 0.1 μ F (100nF) 50V Y5V 0603	0.1 μ F	C0603	0	50V	445-1324-2-ND
300-00116	1	CAP	C25	Kemet	C1210C225K3RACTU	CAP CER 2. μ F 25V 10% X7R 1210	22 μ F	C1210	0	25V	399-3084-1-ND
300-00123	1	CAP	C30	AVX	TLNT227M010R1300	Tantalum Capacitors - Solid SMD 220 μ F 10v 20% Tol ESR = 1300	220 μ F	T3528	20%	10V	581-TLNT227M010R1300
300-00117	2	CAP	C23 C24	Vishay	293D107X9020D2TE3	CAP TANT 100 μ F 20V 10% 2917	100 μ F	C2917P	0	20V	718-1744-1-ND
300-00114	1	CAP	C26	Panasonic	EEE-1VA101XP	CAP ALUM 100 μ F 35V 20% SMD	100 μ F	Radial	0	35V	PCE3951CT-ND
400-00010	1	FET_DIODE	D1	NXP Semi	PMLL4148L,115	DIODE STANDARD 200mA LL-34	200mA	LL-34	0		568-1749-1-ND
400-00002	4	FET_DIODE	D2 D4 D6 D7	Stanley	BR1112H-TR	LEDs SMD 0805 - Red	LED_RED	LED0805	0	2.1V	404-1017-1
400-00001	1	FET_DIODE	D5	Stanley	PG1112H-TR	LED SMD 0805 - Green	LED_GRN	LED0805	0	2.1V	404-1021-1
320-00008	1	CONN	J1			3 pin 100mill standard header	SILH-3	HDR_1x3_100MILL_THRU_HOLE	0		
120-00068	1	CONN	J2	SAMTEC	TSM-107-01-S-DV	CONN. 2X7 HEADER, SMT, DSP JTAG, Pin 6 removed	DSP JTAG Header	hdr_14p	0		
320-00004	1	CONN	J3	Hirose Electric Co Ltd	UX60-MB-5ST	CONN RECEPT MINI USB2.0 5POS	USB-B-mini-smt	female?	0		H2959TR-ND
320-00039	1	CONN	J4	CUI	PJ-037A	CON PWR JCK 2.0 x 6.5MM W/O SW	PWR	thru-hole	0		CP-037A-ND
330-00027	1	MAGNETICS	L1	Coiltronics/Cooper	DR1040-150-R	INDUCTOR POWER SHIELD 15 μ H SMD	15 μ H	DR1040	0		513-1400-1-ND
330-00020	1	MAGNETICS	L2	Panasonic - ECG	ETQ-P5LR60XFA	COIL POWER CHOKE 600nH 27A SMD	600nH	0.571" L x 0.492" W x 0.197" H	0		PCD2022CT-ND
330-00025	2	MAGNETICS	L3 L4	Laird-Signal Integrity Products	HZ0805E601R-10	FERRITE 500mA 600 OHM 0805 SMD	HZ0805E601R-10	805	0	500mA	240-2399-2-ND
330-00041	2	MAGNETICS	L5 L6	Murata	BLM15AX700SN1D	FERRITE CHIP 70 Ω 0402	BEAD	IND0402	0		490-5438-2-ND

Table 4. BOM (continued)

Part No.	QTY.	Part Type	Part Reference	Vendor	Vendor PN	Description	Value	PCB Footprint	Tolerance	Voltage	Distributor Part No.
403-00013	1	POWER	M1-1			Conn header female 2 pos 0.100 mill, Header for PMP7190 custom module AC/DC	PMP7190_Module	HDR_1x2	0		S7035-nd
403-00013	1	POWER	M1-2			Conn header female 2 pos 0.100 mill, Header for PMP7190 custom module AC/DC	PMP7190_Module	HDR_1x2	0		S7035-nd
403-00013	1	POWER	M1-3			Conn header female 2 pos 0.100 mill, Header for PMP7190 custom module AC/DC	PMP7190_Module	HDR_1x2	0		S7035-nd
403-00013	1	POWER	M1-4			Conn header female 2 pos 0.100 mill, Header for PMP7190 custom module AC/DC	PMP7190_Module	HDR_1x2	0		S7035-nd
320-00014	1	CONN	M2	Sullins Connector Solutions	SFH31-NPPB-D17-SP-BK	CONN HDR FMAL 34PS 1.27MM SMD AU	SFH31-NPPB-D17-SP-BK	Female	0		S9117-ND
406-00002	1	Module	M3,P1	FCI	87409-110LF	2x 20P SMT HDR	EM Module	Male	0		649-87409-110LF
406-00002	1	Module	M3,P2	FCI	87409-110LF	2x 20P SMT HDR	EM Module	Male	0		649-87409-110LF
480-00002	4	MTG_HOLE_TP	MH1 MH2 MH3 MH4	TI	280-00002	MTG_HOLE,0.141 hole, 0.25 pad, plated	MH_PL_141	MH_141	0		
320-00036	1	CONN	P1	TE Connectivity	282841-3	TERM BLOCK 3POS SIDE ENT 5.08MM	HV Connector	see datasheet	0		A98343-ND
310-00075	1	RES	R1	Panasonic	ERJ-6GEYJ4R7V	RESISTOR 4.7 Ω 1/8W 5% 0805	4R7	R0805	0		P4.7ACT-ND
110-00031	1	RES	R2	AVX	CR21-105J-*	RESISTOR, 1M, 0.125W, 5%, 0805	1M	R0805	0.05	0.125W	
110-00238	1	RES	R3	Rohm	MCR10EZPJ271	Resistors 270R, 0.125W, 5%, 0805	270R	R0805	0	0.125W	RHM270ARCT-ND
110-00018	3	RES	R4 R5 R6	AVX	CR21-1003F-*	RESISTOR, 100.0K,0.125 W,1 %,0805	100.0K	R0805	0.01	0.125W	
110-00048	1	RES	R7	AVX	CR21-1501F-*	RESISTOR,1.50K, 0.125 W,1 %,0805	1.50K	R0805	0.01	0.125W	
110-00239	1	RES	R8	Rohm	MCR10EZPF2403	Resistors 240K, 0.125W, 1%, 0805	240k	R0805	0	0.125	RHM240KCRCT-ND
310-00104	7	RES	R9 R10 R12 R15 R19 R20 R24	Panasonic	ERJ-2GEJ103X	RES 10kΩ 1/10W 5% 0402 SMD	10k	R0402	0		P10KJTR-ND
110-00179	1	RES	R11	Panasonic	ERJ-3GEYJ104V	RESISTOR,100K, 0.1W, 5%, 0603	100K	R0603	0.05	0.1W	P100KGT-ND
310-00080	3	RES	R13 R16 R27	Panasonic	ERJ-2RKF1001X	RES 1.00kΩ 1/10W 1% 0402 SMD	1k	R0402	0		P1.00KLCT-ND
310-00102	2	RES	R14 R17	Panasonic - ECG	ERJ-2GE0R00X	RES 0.0 Ω 1/10W 0402 SMD	0	R0402	0		P0.0JCT-ND
0402_NP	2	RES	R22 R23			NO POP	0402_NP	R0402			
310-00100	1	RES	R25	Panasonic - ECG	ERJ-2RKF2211X	RES 2.21kΩ 1/10W 1% 0402 SMD	2.21k	R0402	0		P2.21KLCT-ND
310-00103	1	RES	R26	Rohm Semiconductor	MCR01MZPJ681	RES 680 Ω 1/16W 5% 0402 SMD	680	R0402	0		RHM680JCT-ND

Table 4. BOM (continued)

Part No.	QTY.	Part Type	Part Reference	Vendor	Vendor PN	Description	Value	PCB Footprint	Tolerance	Voltage	Distributor Part No.
310-00138	1	RES	R28	Panasonic	ERJ-2RKF1072X	RES 10.7kΩ 1/10W 1% 0402 SMD	10.7k	R0402	0		P10.7KLCT-ND
310-00115	3	RES	R31 R33 R34			RES 82 Ω 0402	82R	R0402	0		
310-00139	1	RES	R32	Panasonic	ERJ-2GEJ680X	RES 68 Ω 1/10W 5% 0402 SMD	68R	R0402	0		P68JCT-ND
310-00140	1	RES	R35	Panasonic	ERJ-2RKF1871X	RES 1.87kΩ 1/10W 1% 0402 SMD	1.87k	R0402	0		P1.87KLCT-ND
310-00113	1	RES	R36	Yageo	RC0805JR-070RL	RES 0.0 Ω 1/8W 0805 SMD	0R	R0805	0		311-0.0ARCT-ND
206-00013	1	SWITCH	SW1	C&K Components	SDA03H1SBD	SWITCH DIP TOP SLIDE 3POS SMD	3POS_DIPSW	3PDIPSW	0		CKN6062-ND
206-00014	1	SWITCH	SW2	C&K Components	SDA02H1SBD	SWITCH DIP TOP SLIDE 2POS SMD	2POS_DIPSW	2PDIPSW	0		CKN6056-ND
206-00015	1	SWITCH	SW3	Mountain Switch	108-2AS1T1203-EVX	Toggle switch SPDT	SPDT	2 thru-hole	0		108-2AS1T1203-EVX
330-00033	1	MAGNETICS	T1	WURTH ELEKTRONIK	750510476	Transformer PLC	750510476	see datasheet	0		
280-00010	1	MTG_HOLE_TP	TP1	TI	TI-TP-60mil	60 mil round test point, SMT	TP_60	TP_60	0		DNP
400-00014	1	FET_DIODE	U1	STMicroelectronics	SM6T10CA	TRANSIL 600W 10V BIDIR SMB	10V	DO-214AA, SMB	0		497-7427-2-ND
402-00069	1	IC	U2	Fairchild Opto	FOD817BSD	Optoisolator, 5000Vrms, 70V	FOD817BSD	4-SMD	0		512-FOD817BSD
402-00070	1	IC	U3	On Semi	BC817-40LT1G	BJT, NPN, I _c =500mA, SOT-23-3	BC817	SOT-23-3	0		BC817-40LT1GOSCT-ND
400-00009	1	FET_DIODE	U4	NXP Semi	BZV55-C5V6,115	DIODE ZENER 500mW 5.6V LL-34	5.6V	LL-34	0		568-3797-1-ND
402-00045	1	IC	U5	FTDI	FT2232HL	IC USB HS DUAL UART/FIFO 64-LQFP	JTAG/UART	64-LQFP	0		768-1024-2-ND
402-00043	1	IC	U6	TI	SN74HC03PWR	IC GATE POS-NAND QD 2IN 14-TSSOP	Quad NAND	14-TSSOP	0		SN74HC03PWR-ND
402-00047	1	IC	U7	TI	TPD2E001DRLR	IC ESD-PROT ARRAY 2CH SOT-5	ESD-PROT	SOT-553	0		296-21883-2-ND
402-00046	1	IC	U8	micro chip	93LC56C-I/SN	IC EEPROM 2KBIT 3MHz 8SOIC	EEPROM	8-SOIC	0		93LC56C-I/SN-ND
402-00072	1	IC	U9	National Semiconductor	LM2941SX/NOPB	IC REG LDO ADJ 1A TO-263-5	LM2941	TO-263-5	0		LM2941SXCT-ND
403-00012	1	POWER	U10	TI	PTH08080WAS	MODULE PIP 0.9-5.5V 2.25A SMD	PTH08080W	PTH_5	0		296-19803-ND
405-00013	1	OSC_XTAL	X1	ECS	ECS-120-20-30B-TR	CRYSTAL 12.000 MHz 20PF SMD	12MHz OSC	4-SMD	0		XC1118TR-ND
300-00131	2	CAP	C31 C32	Kemet	C0805C104K3RACTU	CAP CER 0.1μF 25V 10% X7R 0805	0.1μF	C0805		25V	399-1168-1-ND
402-00056	1	IC	U11	TI	SN74LVC1G57DBVR	Configurable Multiple-function Gate	SN74LVC1G57	SOT-23-6 (DBV)			296-15574-1-ND

7 Gerber Files

To download the Gerber files for each board, see the design files at [TIDA-00192](#).

8 Software Files

To download the software files for the reference design, see the design files at [TIDA-00192](#).

9 About the Author

NAVEEN KUMAR KALA is System Applications Engineer at Texas Instruments, where he is responsible for designing new reference design solutions and software in the Smart Grid segment. He earned his Master of Science in Electrical and Computer Engineering from The University of Iowa, IA.

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